

# Inyoung Kim

## List of Publications by Year in descending order

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Version: 2024-02-01

23  
papers

648  
citations

759233

12  
h-index

677142

22  
g-index

23  
all docs

23  
docs citations

23  
times ranked

920  
citing authors

#	ARTICLE	IF	CITATIONS
1	Silver front electrode grids for ITO-free all printed polymer solar cells with embedded and raised topographies, prepared by thermal imprint, flexographic and inkjet roll-to-roll processes. <i>Nanoscale</i> , 2012, 4, 6032.	5.6	222
2	Transparent conductive film with printable embedded patterns for organic solar cells. <i>Solar Energy Materials and Solar Cells</i> , 2013, 109, 142-147.	6.2	84
3	The effect of reduction atmospheres on the sintering behaviors of inkjet-printed Cu interconnectors. <i>Journal of Applied Physics</i> , 2010, 108, .	2.5	45
4	Reliability of gravure offset printing under various printing conditions. <i>Journal of Applied Physics</i> , 2010, 108, 102802.	2.5	42
5	Roll offset printing process based on interface separation for fine and smooth patterning. <i>Thin Solid Films</i> , 2013, 548, 566-571.	1.8	33
6	Roll-offset printed transparent conducting electrode for organic solar cells. <i>Thin Solid Films</i> , 2015, 580, 21-28.	1.8	29
7	Effect of ink cohesive force on gravure offset printing. <i>Microelectronic Engineering</i> , 2012, 98, 587-589.	2.4	25
8	Investigation on synchronization of the offset printing process for fine patterning and precision overlay. <i>Journal of Applied Physics</i> , 2014, 115, 234908.	2.5	25
9	Flash light sintering of ag mesh films for printed transparent conducting electrode. <i>Thin Solid Films</i> , 2017, 629, 60-68.	1.8	25
10	Tension modeling and precise tension control of roll-to-roll system for flexible electronics. <i>Flexible and Printed Electronics</i> , 2021, 6, 015005.	2.7	16
11	IoT device fabrication using roll-to-roll printing process. <i>Scientific Reports</i> , 2021, 11, 19982.	3.3	16
12	Registration error analysis and compensation of roll-to-roll screen printing system for flexible electronics. <i>Flexible and Printed Electronics</i> , 2021, 6, 024003.	2.7	15
13	Employment of roll-offset printing for fabrication of solder bump arrays: Harnessing the rheological properties of lead-free solder pastes using particle size distribution. <i>Microelectronic Engineering</i> , 2016, 164, 128-134.	2.4	13
14	Hybrid fabrication of LED matrix display on multilayer flexible printed circuit board. <i>Flexible and Printed Electronics</i> , 2021, 6, 024001.	2.7	13
15	Hybrid electrohydrodynamic atomization of nanostructured silver top contact for inverted organic solar cells. <i>Solar Energy Materials and Solar Cells</i> , 2014, 130, 156-162.	6.2	11
16	Quantitative measurement of ink-blanket adhesion for contact transfer printing inks. <i>International Journal of Precision Engineering and Manufacturing</i> , 2015, 16, 151-156.	2.2	9
17	Experimental Qualification of the Process of Electrostatic Spray Deposition. <i>Coatings</i> , 2019, 9, 294.	2.6	9
18	Mechanical and electrical properties of reverse-offset printed Sn-Ag-Cu solder bumps. <i>Journal of Materials Processing Technology</i> , 2018, 259, 126-133.	6.3	6

#	ARTICLE	IF	CITATIONS
19	Effect of particle size distribution on the mechanical and electrical properties of reverse-offset printed Sn–Ag–Cu solder bumps. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 19620-19631.	2.2	3
20	Al-assisted reliability assessment for gravure offset printing system. <i>Scientific Reports</i> , 2022, 12, 2954.	3.3	3
21	Fabrication of replica cliché with fine pattern using reverse offset printing process. <i>Thin Solid Films</i> , 2018, 647, 57-63.	1.8	2
22	Improvement of electrical and mechanical properties of In-48Sn solder bumps for flexible LED signage using Cu-Ag nanoparticles. <i>Flexible and Printed Electronics</i> , 2021, 6, 034006.	2.7	2
23	Cliché fabrication method using precise roll printing process with 5 um pattern width. <i>Proceedings of SPIE</i> , 2016, , .	0.8	0